



LDB10X Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu).	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 28.04%	Copper (Cu)	7440-50-8	93.9900	99.9787	280,381.4
	Phosphorus (P)	7723-14-0	0.0009	0.0010	2.8
	Arsenic (As)	7440-38-2	0.0009	0.0010	2.8
	Tin (Sn)	7440-31-5	0.0009	0.0010	2.8
	Oxygen (O)	7782-44-7	0.0005	0.0005	1.4
	Sulfur (S)	7704-34-9	0.0113	0.0120	33.6
	Iron (Fe)	7439-89-6	0.0006	0.0007	1.8
	Nickel (Ni)	7440-02-0	0.0003	0.0003	0.8
	Bismuth (Bi)	7440-69-9	0.0019	0.0020	5.6
	Antimony (Sb)	1309-64-4	0.0019	0.0020	5.6
	Lead (Pb)	7439-92-1	0.0005	0.0005	1.4
	Zinc (Zn)	7440-66-6	0.0003	0.0003	0.8
	Total			94.01	
Solder Wafer 1.31%	Lead (Pb)	7439-92-1	4.06	92.50	1,211.9
	Tin (Sn)	7440-31-5	0.22	5.00	65.5
	Silver (Ag)	7440-22-4	0.11	2.50	32.8
	Total			4.39	
Chip 1.07%	Silicon (Si)	7440-21-3	3.60	100.00	1,073.9
	Total			3.60	
Molding 69.3%	Epoxy	25928-94-3	232.30	100.00	69,297.4
	Total			232.30	
Plating 0.28%	Tin (Sn)	7440-31-5	0.92	100.00	274.4
	Total			0.92	
Total mass (mg)			335.22		